

#### **PATENT**

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.:

10/573,833

Filing Date:

March 29, 2006

Applicant:

Yasuo SUDA et al.

Group Art Unit:

Unassigned

Examiner:

Unassigned

Title:

METALLIC THIN FILM CHIP PRODUCING METHOD

AND METALLIC THIN FILM CHIP PRODUCING

APPARATUS (as amended)

Attorney Docket:

12480-000171/US

Customer Service Window Randolph Building 401 Dulany Street Alexandria, VA 22314 Mail Stop Amendment July 14, 2006

## INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant hereby submits an Information Disclosure Statement for consideration by the Examiner.

### I. <u>LIST OF PATENTS, PUBLICATIONS, AND OTHER INFORMATION</u>

The patents, publications and other information submitted for consideration by the Office (except unpublished U.S. patent applications) are listed on Form PTO-1449 attached hereto.

#### II. COPIES

A. Submitted herewith is a legible copy of (i) each foreign patent; (ii) each
publication or that portion which caused it to be listed, other than U.S. patents and U.S.
patent application publications unless required by the Office; (iii) for each cited
pending unpublished U.S. application listed below in Section IV, the application
specification including the claims, and any drawing of the application, or that portion of
the application which caused it to be listed including any claims directed to that portion;
and (iv) all other information or that portion which caused it to be listed.

B. Any patents, publications or other information which are listed on Form PTO-1449 or on the copies of Form PTO-892, but which are not enclosed herewith,

were previously cited by or submitted to the PTO in one of the following applications which has been relied upon for an earlier filing date under 35 U.S.C. § 120:

# U.S. Serial Number

U.S. Filing Date

	C. Because the present application was/is being filed after June 30, 2003, no copies of the U.S. patents or U.S. patent application publications which are listed on the attached Form PTO-1449 are enclosed pursuant to the waiver of 37 C.F.R. § 1.98(a)(2)(i). Any foreign patent documents or non-patent literature listed on the attached Form PTO-1449 are enclosed herewith.
	D. This is a PCT application in the entry of the National Phase in the United States. A copy of the International Search Report is attached for the Examiner's information. The documents listed on the International Search Report are listed on the attached Form PTO-1449 for consideration by the Examiner and for listing on any patent resulting from this application. Since the International Search Report was from the US, EPO, or JPO search authorities, copies of these references should have been supplied to the USPTO under the trilateral agreement and are believed to be in the file of the above-identified application. (MPEP 1893.03(g))
III.	CONCISE EXPLANATION OF THE RELEVANCE (check at least one box)
	A. Except as may be indicated below in (B), all of the patents, publications or other information are in the English language (concise explanation not required).
	B. \( \sum A\) concise explanation of the relevance of each patent, publication or other information listed that is not in the English language is as follows (see 37 C.F.R. \( \) \( 1.98(a)(3)):
	<ol> <li>See the attached foreign patent office communication from a counterpart foreign application:</li> <li>English abstracts are provided for: JP 10-267834, JP 11-006834, JP 2002-257720, JP 2003-161694 and JP 2003-254904.</li> <li>Other: Relevance Statements are provided for JP 10-267834, JP 11-006834, JP 2002-257720, JP 2003-161694 and JP 2003-254904 and "Production of Au Thin Film Chip by Microwave Heating". English translation is provided for "Information on High-Frequency Induction Heating Technique".</li> </ol>
	C. The following additional information is provided for the Examiner's consideration. US. Patent Application Publication corresponds to JP 2003-75447 submitted with the 3/29/2006 IDS.
IV.	CROSS REFERENCE TO RELATED APPLICATION(S)
	A. The Examiner is advised that the following co-pending application(s) contain(s) subject matter that may be related to the present application. By bringing this(these)

application(s) to the Examiner's attention, Applicant(s) does(do) not waive the confidentiality provisions of 35 U.S.C. § 122.

Serial No.

Filing Date

Art Unit

## V. THIS IDS IS BEING FILED UNDER

A. X 37 C.F.R. § 1.97(b): (check <u>only</u> one box)
1. within three months of the filing date of a national application other than a continued prosecution application under 37 C.F.R. § 1.53(d) (37 C.F.R. § 1.97(b)(1)). No fee or certification is required.
2. within three months of the date of entry of the national stage as set forth in 37 C.F.R. §1.491 in an international application (37 C.F.R. § 1.97(b)(2)). No fee or certification is required.
3. before the mailing of a first Office Action on the merits (37 C.F.R. § 1.97(b)(3)). No fee or certification is required. In the event that a first Office Action on the merits has been issued, please consider this IDS under 37 C.F.R. § 1.97(c) and see the certification under 37 C.F.R. § 1.97(e) below; or, if no certification has been made, charge our deposit account a fee in the amount of \$180.00 as required by 37 C.F.R. § 1.17(p).
4.  before the mailing of a first Office Action after the filing of a request for continued examination under 37 C.F.R. § 1.114. No fee or certification is required.
B. 37 C.F.R. § 1.97(c): (check only one box)
before the mailing date of either any Final Office Action under 37 C.F.R. § 1.113, a Notice of Allowance under 37 C.F.R. § 1.311, or an action that otherwise closes prosecution.
1. No certification; therefore, a fee in the amount of \$180.00 is required by 37 C.F.R. § 1.17(p).
2. See the certification below. No fee is required.
C. 37 C.F.R. § 1.97(d):

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	after the mailing date of either a Final Office Action under 37 C.F.R. § 1.113 or a Notice of Allowance under 37 C.F.R. § 1.311, yet on or before payment of the issue fee.
	1. See the certification below. A fee in the amount of \$180.00 is required by 37 C.F.R. § 1.17(p).
VI.	CERTIFICATION UNDER 37 C.F.R. § 1.97(e): (check only one box)
	The undersigned hereby certifies that:
	A. a each item of information contained in this IDS was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this IDS (See 37 C.F.R. § 1.97(e)(1)). See further statement under 37 C.F.R. § 1.704(d) below in section VII, if applicable; or
	B. no item of information contained in this IDS was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned after making reasonable inquiry, no item of information contained in this IDS was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of this IDS (See 37 C.F.R. § 1.97(e)(2)).
	C. Some of the items of information were first cited in a communication from a foreign patent office. As to this information, the undersigned hereby certifies that each item of information contained in this IDS was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this IDS. As to the remaining information, the undersigned hereby certifies that no item of this remaining information contained in this IDS was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned after making reasonable inquiry, no item of information contained in this IDS was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of this IDS.
VII.	STATEMENT UNDER 37 C.F.R. § 1.704(d)
	The undersigned hereby states that:
foreig	each item of information contained in this IDS was cited in a communication from a patent office in a counterpart application and this communication was not received by adividual designated in 37 C.F.R. § 1.56(c) more than thirty days prior to the filing of this

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VIII.	<u>PAYM</u>	ENT O	F FEES (	check <u>only</u>	one box)			
	A. 🛛 1	No fee i	is believed	to be due.				
	В. 🗌 А	A check	in the am	ount of \$18	0.00 is enclos	sed for the ab	ove-identi	fied fee.
						50 in the amper is attached		80.00 for the
or whi	sion that ich wou ry skill	they co ld rend in the	nstitute stater the san art. Furth	atutory prion ne obvious, nermore, thi	art, contain either singl	matter which y or in com n Disclosure	anticipates bination, to	I without any the invention, a person of shall not be
_	ted to co	nsider	this IDS u		oper rule (wi			e, the PTO is y) and charge
§§ 1.1				ional fees ount No. 08-		overpaymen	t pursuant	to 37 C.F.R.
					Respectfull	y submitted,		
					HARNESS,	, DICKEY, &	z PIERCE,	P.L.C.
					P.O. Box 89		No. 41,060	)
					Reston, Vir. (703) 668-8	=		
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### FORM HDP-1449 (Based on Form PTO-1449)

PATENT AND TRADEMARK OFFICE F INFORMATION DISCLOSURE CATION (Use several sheets if necessary)

Sheet 1 of 1

ATTORNEY DOCKET No.	SERIAL NO.				
12480-000171/US	10/573,833				
APPLICANT					
Yasuo SUDA et al.					
FILING DATE	GROUP				
March 29, 2006	Unassigned				

U.S. PATENT DOCUMENTS							
Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date	
		2003/0073245 A1	04/17/2003	Shinoki et al.			
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FOREIGN PATENT DOCUMENTS							
Ref. Desig.	Examiner's Initials	Document Number	Date	Country	Class/ Subclass	Translation Yes	ı No
		10-267834	10/09/1998	JAPAN		Abstract	
		11-006834	01/12/1999	JAPAN		Abstract	
-		2002-257720	09/11/2002	JAPAN		Abstract	
		2003-161694	06/06/2003	JAPAN		Abstract	
		2003-254904	09/10/2003	JAPAN		Abstract	

OTHER	OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)					
Ref. Desig.	Examiner's Initials					
		SPC Electronics Corporation, <a href="http://www.spc.co.jp/heating/tec_002.htm">http://www.spc.co.jp/heating/tec_002.htm</a> , "Information on High-Frequency Induction Heating Technique,"				
		Shigeki KAKIUCHI et al., "Production of Au Thin Film Chip by Microwave Heating," Collected abstracts of the 2005 Autumn Meeting of the Japan Institute of Metals, September 2005, pg. 62				

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Examiner:	Date Considered:	